

Features

- Industry-standard quarter-brick pinout
- Delivers 240W at 94.2% efficiency
- Withstands 100V input transient for 100ms
- Fixed-frequency operation
- On-board input differential LC-filter
- Start-up into pre-biased load
- No minimum load required
- Meets Basic Insulation requirements
- Fully protected (OTP, OCP, OVP, UVLO)
- Positive or negative logic ON/OFF option
- Low height of 0.44" (11.18mm)
- Weight: 32g w/o baseplate, 40g with baseplate
- High reliability: MTBF = 14.3 million hours, calculated per Telcordia SR-332, Method I Case 1
- Approved to the following Safety Standards: UL/CSA60950-1, EN60950-1, and IEC60950-1
- Designed to meet Class B conducted emissions per FCC and EN55022 when used with external filter
- All materials meet UL94, V-0 flammability rating

SQE48T20120 DC-DC Converter

36-75VDC Input; 12VDC, 20A, 240W Output

The new high performance 20A **SQE48T20120** DC-DC converter provides a high efficiency single output, in a 1/8th brick package that is only 62% the size of the industry-standard quarter-brick. Specifically designed for operation in systems that have limited airflow and increased ambient temperatures, the SQE48T20120 converter utilizes the same pinout and Input/Output functionality of the industry-standard quarter-bricks. In addition, a heat-spreader (baseplate) feature is available (-xDxBx suffix) that provides an effective thermal interface for coldplate and heat sinking options.

The SQE48T20120 converter thermal performance is accomplished through the use advanced circuits, packaging, and processing techniques to achieve ultra-high efficiency, excellent thermal management, and a low-body profile.

Operating from a wide-range 36-75V input, the SQE48T20120 converter provides a fully regulated 12V output voltage. Employing a standard power pinout, the SQE48T20120 converter is an ideal drop-in replacement for existing high current quarter-brick designs. Inclusion of this converter in a new design can result in significant board space and cost savings. The designer can expect reliability improvement over other available converters because of the SQE48T20120's optimized thermal efficiency.

Applications

- Intermediate Bus Architectures
- Data communications/processing
- LAN/WAN
- Servers, Workstations

Benefits

- High efficiency no heat sink required¹
- Industry-standard 1/8th brick footprint: 0.896" x 2.30"
 (2.06 in²) 38% smaller than conventional quarter-bricks

¹Baseplate/heat-spreader option (suffix '-xDxBx') facilitates heatsink mounting to further enhance the unit's thermal capability.

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1 Electrical Specifications

Conditions: $T_A = 25$ °C, Airflow = 300 LFM (1.5 m/s), Vin = 48 VDC, Cin=100 μ F, unless otherwise specified.

PARAMETER		NOTES	MIN	TYP	MAX	UNITS
Absolute Maximum Ratings						
land Vallana		Continuous	-0.3		80	VDC
Input Voltage		Transient (100ms)			100	VDC
Operating Temperature		Ambient (T _A)	-40		85	°C
		1Component (T _C)	-40		125	°C
(See Derating Curves)		Baseplate (T _B)	-40		105	°C
Storage Temperature			-55		125	°C
Isolation Characteristics						
I/O Isolation		Dielectric strength	2,250			VDC
Isolation Capacitance		UL/CSA60950-1, EN60950-1, and IEC60950-1.		1200		pF
Isolation Resistance		Basic Insulation	10			МΩ
Input to Baseplate			1,500			VDC
Output to Baseplate			1,500			VDC
Feature Characteristics						
Switching Frequency			428	450	502	kHz
Output Voltage Trim Range ²				n/a		%
Remote Sense Compensation ²				n/a		%
Output Overvoltage Protection	(Non-latching)		110	120	130	%
Over Temperature Shutdown	(Non-latching)	² Component (T _C)		130		°C
Auto-Restart Period		Applies to all protection features		250		ms
Turn-On Time from Vin		Time from UVLO to Vo=90%VouT(NOM) Resistive load		22	25	ms
Turn-On Time from ON/OFF Co	ntrol	Time from ON to Vo=90%VouT(NOM) Resistive load		12	15	ms
Turn-On Time from Vin (w/ Co max.)		Time from UVLO to Vo=90% $V_{OUT}(NOM)$ Resistive load, C_{EXT} =10,000 μ F load		22	25	ms
Turn-On Time from ON/OFF Co (w/ Co max.)	ntrol	Time from ON to Vo=90%Vout(NOM) Resistive load, C _{EXT} =10,000µF load		12	15	ms
ON/OFF Control (Positive Logic))	Converter Off (logic low)	-20		8.0	VDC
3 . ,		Converter On (logic high)	2.4		20	VDC
ON/OFF Control (Negative Logic	c)	Converter Off (logic low)	2.4		20	VDC
	-,	Converter On (logic high)	-20		8.0	VDC
Input Characteristics						
Operating Input Voltage Range			36	48	75	VDC
Input Undervoltage Lockout						
Turn-on Threshold			31.5	34.5	35.5	VDC
Turn-off Threshold			30	32	34.0	VDC
Lockout Hysteresis Voltage			1.5	2.0	2.5	VDC
Maximum Input Current		Po = 240W @ 36VDC In			7.3	ADC
Input Standby Current		Vin = 48V, converter disabled		3	5	mA
Input No Load Current (No load	on the output)	Vin = 48V, converter enabled	50	70	130	mA
Input Reflected-Ripple Current,	ic			760	900	mA_{PK-PK}



	Vin = 48V, 25 MHz bandwidth,		265	325	mA _{RMS}
Input Reflected-Ripple Current, is	Po=240W (Figs. 19, 20, 21)		8	14	mA _{PK-PK}
input richected rippie durient, is	, ,		2	5	mA_RMS
Input Voltage Ripple Rejection	120 Hz		45		dB
Output Characteristics					
Output Voltage Setpoint	V_{IN} =48V, I_{OUT} =0Amps, T_A =25°C	11.76	12.00	12.24	VDC
Output Regulation					
Over Line	I _{OUT} =20Amps, T _A =25°C		±12	±24	mV
Over Load	V_{IN} =48V, , T_A =25°C		±6	±12	mV
Output Voltage Range	Over line, load and temperature	11.64		12.36	VDC
Output Dipple and Naise OF MUz handwidth	louт=20Amps,		50	100	$mV_{\text{PK-PK}}$
Output Ripple and Noise – 25 MHz bandwidth	$C_{EXT} = 10 \mu\text{F}$ tantalum + 1 μF ceramic		25	50	V_{RMS}
Admissible External Load Capacitance	I_{OUT} =20Amps (resistive) C_{EXT} ESR	0 ³ 1		10,000	μF mOhm
Output Current Range		0		20	ADC
Current Limit Inception	Non-latching	22	25	29	ADC
RMS Short-Circuit Current	Non-latching Short = 10 m Ω		2.4	5	ARMS
Dynamic Response					
Load Change 50%-75%-50% of I_{OUT} Max (di/dt = 0.1 A/ μ s)	$C_{EXT} = 10\mu F tantalum + 1\mu F ceramic$		75	140	mV
Settling Time to 1% of Vout			30	50	μs
Efficiency					
@ 100% Load	49V T -25°C 2001 EM		94.2		%
@ 60% Load	48V _{IN} , T _A =25°C, 300LFM		94		%
Defending Circums C for assessment (T. and T.) les	ations				

2 Environment and Mechanical Specifications

PARAMETER	NOTES	MIN	TYP	MAX	UNITS
Environmental					
Operating Humidity	Non-condensing			95	%
Storage Humidity	Non-condensing			95	%
Mechanical					
Weight	Without baseplate		32		g
Weight	With baseplate		40		g
Vibration	GR-63-CORE, Sect. 5.4.2	1			g
Shocks	Half Sinewave, 3-axis	50			g
Reliability					
MTBF	Telcordia SR-332, Method I Case 1 50% electrical stress, 40°C components		14.3		MHrs
EMI and Regulatory Compliance					
Conducted Emissions	CISPR 22 B with external EMI filter network				



⁷Reference Figure E for component (T_C and T_B) locations. ²This functionality not provided, however the unit is fully regulated. ³See "Input Output Impedance", Page 4

3 Operations

3.1 Input and Output Impedance

These power converters have been designed to be stable with no external capacitors when used in low inductance input and output circuits.

However, in some applications, the inductance associated with the distribution from the power source to the input of the converter can affect the stability of the converter. A 100 μ F electrolytic capacitor with adequate ESR based on input impedance is recommended to ensure stability of the converter.

In many end applications, a high capacitance value is applied to the converter's output via distributed capacitors. The power converter will exhibit stable operation with external load capacitance up to 10,000 µF.

3.2 ON/OFF (PIN 2)

The ON/OFF pin is used to turn the power converter on or off remotely via a system signal. There are two remote control options available, positive and negative logic, with both referenced to Vin(-). A typical connection is shown in Figure A.

The positive logic version turns on when the ON/OFF pin is at a logic high or left open and turns off when it is at a logic low. See the Electrical Specifications for logic high/low definitions.

Vin (+) SQE48 Converter Vout (+)

ON/OFF

Vin (-)

Vout (-)

Fig. A: Typ. Circuit configuration for ON/OFF function

The negative logic version turns on when the ON/OFF pin is at a logic low and turns off when the pin is at logic high. To enable automatic power up of the converter without the need of an external control signal the ON/OFF pin can be hard wired directly to Vin(-) for N and left open for P version.

The ON/OFF pin is internally pulled up to 5V through a resistor. A properly de-bounced mechanical switch, open-collector transistor, or FET can be used to drive the input of the ON/OFF pin. The device must be capable of sinking up to 0.2 mA at a low level voltage of \leq 0.8 V. An external voltage source (\pm 20 V maximum) may be connected directly to the ON/OFF input, in which case it must be capable of sourcing or sinking up to 1 mA depending on the signal polarity. See the Startup Information section for system timing waveforms associated with use of the ON/OFF pin.

4 Protection Features

4.1 Input Undervoltage lockout (UVLO)

Input undervoltage lockout is standard with this converter. The converter will shut down when the input voltage drops below a pre-determined voltage.

The input voltage must be typically 35V for the converter to turn on. Once the converter has been turned on, it will shut off when the input voltage drops typically below 33V. This feature is beneficial in preventing deep discharging of batteries used in telecom applications.

4.2 Output Overcurrent Protection (OCP)

The converter is protected against overcurrent or short circuit conditions. Upon sensing an overcurrent condition, the converter will shut down after entering the constant current mode of operation, regardless of the value of the output voltage.

Once the converter has shut down, it will enter hiccup mode with attempt to restart every 260ms until the overload or short circuit conditions are removed.



4.3 Output Overvoltage Protection (OVP)

The converter will shut down if the output voltage across Vout(+) and Vout(-) exceeds the threshold of the OVP circuitry. The OVP circuitry contains its own reference, independent of the output voltage regulation loop. Once the converter has shut down, it will attempt to restart every 260 ms until the OVP condition is removed.

4.4 Overtemperature Protection (OTP)

The converter will shut down under an overtemperature condition to protect itself from overheating caused by operation outside the thermal derating curves, or operation in abnormal conditions. The converter will automatically restart after it has cooled to a safe operating temperature.

4.5 Safety Requirements

The converters are safety approved to UL/CSA60950-1, EN60950-1, and IEC60950-1. Basic Insulation is provided between input and output.

The converters have no internal fuse. To comply with safety agencies requirements, an input line fuse must be used external to the converter. A 10A fuse is recommended for use with this product. The fuse must not be placed in the grounded input line.

The SQE48 converter is UL approved for a maximum fuse rating of 15Amps.

4.6 Electromagnetic Compatibility (EMC)

EMC requirements must be met at the end-product system level, as no specific standards dedicated to EMC characteristics of board mounted component dc-dc converters exist. However, Bel Power Solutions tests its converters to several system level standards, primary of which is the more stringent EN55022, Information technology equipment - Radio disturbance characteristics - Limits and methods of measurement.

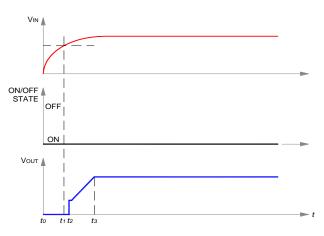
An effective internal LC differential filter significantly reduces input reflected ripple current, and improves EMC.

With the addition of an external filter, the SQE48T20120 converter will pass the requirements of Class B conducted emissions per EN55022 and FCC requirements. Refer to Figures 18 – 19 for typical performance with external filter.

4.7 Startup Information (Using Negative ON/OFF)

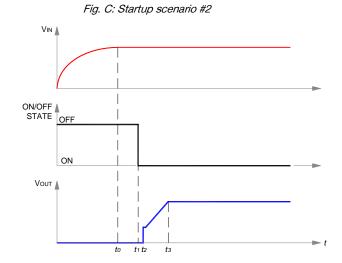
Scenario #1: Initial	Startup From Bulk Supply						
ON/OFF function enabled, converter started via application							
of V _{IN} . See Figure B	·						
Time	Comments						
t ₀	ON/OFF pin is ON; system front-end						
	power is toggled on, V _{IN} to converter						
	begins to rise.						
t ₁	V _{IN} crosses undervoltage Lockout						
	protection circuit threshold; converter						
	enabled.						
t ₂	Converter begins to respond to turn-on						
_	command (converter turn-on delay).						
t ₃	Converter Vour reaches 100% of						
	nominal value.						
For this example, th	ne total converter startup time (t ₃ - t ₁) is						
typically 22 ms.	10 total 0011101101 otal tap 111110 (10 11) 10						
typically 22 IIIS.							

Fig. B: Startup Scenario #1



typically 12 ms.

Scenario #2: Initial Startup Using ON/OFF Pin With V_{IN} previously powered, converter started via ON/OFF pin. See Figure C. Time Comments t_0 VINPUT at nominal value. Arbitrary time when ON/OFF pin is t_1 enabled (converter enabled). End of converter turn-on delay. t_2 tз Converter V_{OUT} reaches 100% of nominal value. For this example, the total converter startup time (t_3 - t_1) is



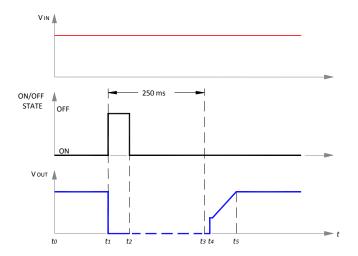
Scenario #3: Turn-off and Restart Using ON/OFF Pin

With V_{IN} previously powered, converter is disabled and then enabled via ON/OFF pin. See Figure D.

enabled via ON/	OFF pin. See Figure D.
Time	Comments
t_0	V _{IN} and V _{OUT} are at nominal values; ON/OFF pin ON.
t ₁	ON/OFF pin arbitrarily disabled; converter output falls to zero; turn-on inhibit delay period (300 ms typical) is initiated, and
t_2	ON/OFF pin action is internally inhibited. ON/OFF pin is externally re-enabled.
	If (t₂- t₁) ≤ 250 ms, external action of ON/OFF pin is locked out by startup inhibit timer. If (t₂- t₁) > 250 ms, ON/OFF pin action is internally enabled.
t_3	Turn-on inhibit delay period ends. If ON/OFF pin is ON, converter begins turn-on; if off, converter awaits ON/OFF pin ON signal; see Figure F.
t ₄ t ₅	End of converter turn-on delay. Converter V _{OUT} reaches 100% of nominal value.

For the condition, $(\mathbf{t_2-t_1}) \leq 250 \, \text{ms}$, the total converter startup time $(\mathbf{t_{5^-}t_1})$ is typically 272ms. For $(\mathbf{t_{2^-}t_1}) > 250 \, \text{ms}$, startup will be typically 22ms after release of ON/OFF pin.

Fig. D: Startup scenario #3.





5 Characterization

5.1 General Information

The converter has been characterized for many operational aspects, to include thermal derating (maximum load current as a function of ambient temperature and airflow), efficiency, startup and shutdown parameters, output ripple and noise, transient response to load step-change, overcurrent, and short circuit.

The following pages contain specific plots or waveforms associated with the converter. Additional comments for specific data are provided below.

5.2 Test Condtions

All data presented were taken with the converter soldered to a test board, specifically a 0.060" thick printed wiring board (PWB) with four layers. The top and bottom layers were not metalized. The two inner layers, comprised of two-ounce copper, were used to provide traces for connectivity to the converter.

The lack of metallization on the outer layers as well as the limited thermal connection ensured that heat transfer from the converter to the PWB was minimized. This provides a worst-case but consistent scenario for thermal derating purposes.

All measurements requiring airflow were made in the vertical and horizontal wind tunnel using Infrared (IR) thermography and thermocouples for thermometry.

Ensuring components on the converter do not exceed their ratings is important to maintaining high reliability. If one anticipates operating the converter at or close to the maximum loads specified in the derating curves, it is prudent to check actual operating temperatures in the application. Thermographic imaging is preferable; if this capability is not available, then thermocouples may be used. The use of AWG #40 gauge thermocouples is recommended to ensure measurement accuracy. Careful routing of the thermocouple leads will further minimize measurement error. Refer to Figure E for the optimum measuring thermocouple location.

5.3 Thermal Derating - Air Cooled

Load current vs. ambient temperature and airflow rates are given in Figures 1 for converter w/o base plate, and in Figure 7 and 8 for converter with Baseplate and 0.25" and 0.5" tall heatsink, respectively. Ambient temperature was varied between 25°C and 85°C, with airflow rates from 30 to 500LFM (0.15 to 2.5m/s).

For each set of conditions, the maximum load current was defined as the lowest of:

- (i) The output current at which any FET junction temperature does not exceed a maximum temperature of 125°C as indicated by the thermal measurement.
- (ii) The output current at which the temperature at the thermocouple locations T_{C1} and T_{C2} do not exceed 125°C (Figure E).
- (iii) The nominal rating of the converter (20A/240W).

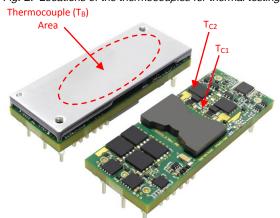


Fig. E: Locations of the thermocouples for thermal testing

5.4 Thermal Derating - Baseplate Coled (P/N: -XGXBX)

The maximum load current rating vs. baseplate temperature is provided in Figure 9. The ambient temperature of the converter was maintained ≤ 85 °C, with an airflow rate of ≤ 30 LFM (≤ 0.15 m/s).

Thermocouple measurements were maximized, as above, to the following limits:



 $T_{C1} \le 125^{\circ}C$, $T_{C2} \le 125^{\circ}C$ & $T_{B} \le 105^{\circ}C$.

The user should design for $T_B \le 105$ °C.

Note that use of baseplate alone without heatsink or attachment to cold plate provides lower power rating then open frame unit due to the present baseplate temperature limitation of 105°C.

5.5 Efficiency

Figure 10 shows the efficiency vs. load current plot for ambient temperature (T_A) of 25°C, airflow rate of 300LFM (1.5m/s) with vertical mounting and input voltages of 36V, 48V, and 75V.

Efficiency vs. load current and ambient temperature for converter w/o baseplate mounted vertically with Vin = 48 V and air flowing from pin 3 to pin 1 at a rate of 200 LFM (1.0 m/s) is shown in Figure 12.

5.6 Power Dissipation

Figure 11 shows the power dissipation vs. load current for T_A=25°C, airflow rate of 300LFM (1.5m/s) with vertical mounting and input voltages of 36V, 48V, and 75V.

Figure 1 shows the power dissipation vs. load current and ambient temperature for converter w/o baseplate mounted vertically with Vin = 48 V and air flowing from pin 3 to pin 1 at a rate of 200 LFM (1.0 m/s).

5.7 Startup

Output voltage waveforms, during the turn-on transient using the ON/OFF pin for full rated load currents (resistive load) are shown with and without external load capacitance in Figure 14 and 15, respectively.

5.8 Ripple and Noise

Figure 18 shows the output voltage ripple waveform, measured at full rated load current with a $10\mu F$ tantalum and a $1\mu F$ ceramic capacitor across the output. Note that all output voltage waveforms are measured across the $1\mu F$ ceramic capacitor.

The input reflected-ripple current waveforms are obtained using the test setup shown in Figure 19. The corresponding waveforms are shown in Figure 20 and Figure 21.

5.9 Thermal Considerations

In general, high density power converter modules built with integrated baseplates are selected when they are to interface with the users' cold plate, bulkhead or other physical heat sinking surface. Baseplates alone <u>do not</u> necessarily improve the power converter's power capability when compared to the same module without baseplate.

Output power de-rating charts are provided for modules both with and without an integrated baseplate.

Figure 1: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from pin 3 to pin 1, MOSFET temperature ≤ 125°C, Vin = 48 V.¹

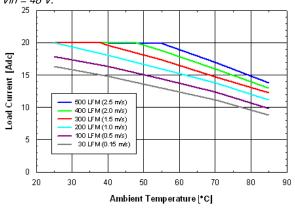
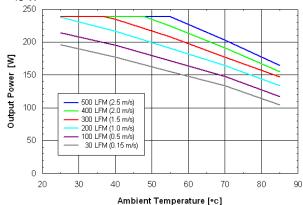


Figure 2: Available output power vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from pin 3 to pin 1, MOSFET temperature ≤ 125°C, Vin = 48 V.¹



All performance charts below (Fig. 3 thru 9) reflect modules with integrated baseplates.

Figures 3 - 6: Power derating with the baseplate temperature (T_{BP}) maintained ≤ 115°C and T_J ≤ 120°C.

Figures 7 - 9: Power derating with T_{BP} maintained ≤ 105°C and T_J ≤ 110°C. (with approved *Operational insulation* (to 2.250Vpc))



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20

30

Figure 3: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from pin 3 to pin 1, MOSFET temperature ≤

120°C, Vin = 48 V (nom.).²

25

20

20

25

40 LFM (2.5 m/s)

400 LFM (2.0 m/s)

300 LFM (1.5 m/s)

200 LFM (1.5 m/s)

300 LFM (0.5 m/s)

30 LFM (0.15 m/s)

Figure 5: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from In/Out, MOSFET temperature \leq 120 °C, $Vin = 48 \ V (nom.)$.

Ambient Temperature [°C]

9n

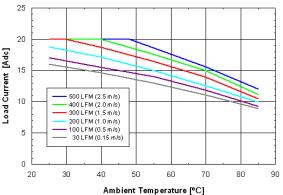


Figure 7: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter with baseplate option and 0.25" tall transverse-fin heatsink.

Unit mounted vertically with air flowing from pin 3 to pin 1, $Vin = 48 \text{ V (nom.)}.^4$

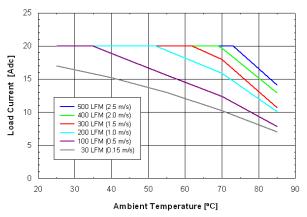


Figure 4: Available output power vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from pin 3 to pin 1, MOSFET

temperature ≤ 120 °C, Vin = 48 V (nom.).2

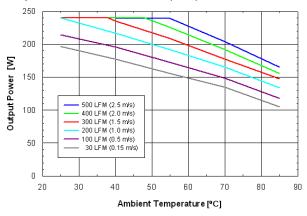


Figure 6: Available output power vs. ambient air temperature and airflow rates for SQE48T20120 converter mounted vertically with air flowing from In/Out, MOSFET temperature ≤ 120 °C, Vin = 48 V (nom.).³

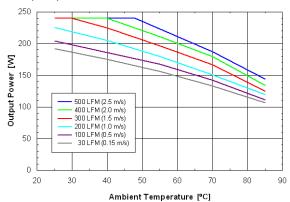


Figure 8: Available load current vs. ambient air temperature and airflow rates for SQE48T20120 converter with baseplate option and 0.5" tall transverse-fin heatsink.

Unit mounted vertically with air flowing from pin 3 to pin 1, Vin = 48 V (nom.).4

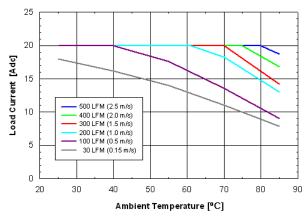
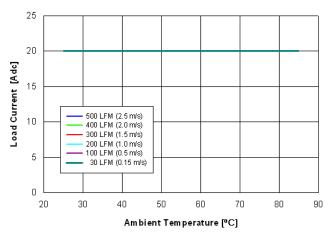




Figure 9: Power derating of SQE48T20120 converter with baseplate option and <u>cold plate</u> <u>cooling</u>. (Conditions: $T_B \le 105^{\circ}\text{C}$, $T_A \le 85^{\circ}\text{C}$, Air velocity $\le 30\text{LFM}$ ($\le 0.15\text{m/s}$), Vin = $48V.^4$



¹Figures 1 & 2 <u>without</u> Baseplate, <u>Transverse</u> airflow, T_J ≤ 125°C

Figure 10: Efficiency vs. load current and input voltage for converter w/o baseplate mounted vertically with air flowing from pin 3 to pin 1 at a rate of 300 LFM (1.5 m/s) and Ta = 25 °C.

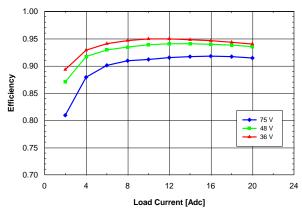


Figure 12: Efficiency vs. load current and ambient temperature for converter w/o baseplate mounted vertically with Vin = 48 V and air flowing from pin 3 to pin 1 at a rate of 200 LFM (1.0 m/s).

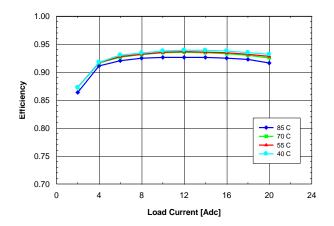


Figure 11: Power dissipation vs. load current and input voltage for converter w/o baseplate mounted vertically with air flowing from pin 3 to pin 1 at a rate of 300 LFM (1.5 m/s) and Ta = 25 °C.

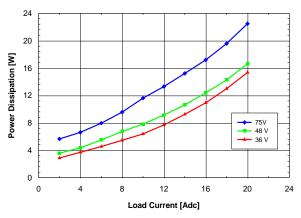
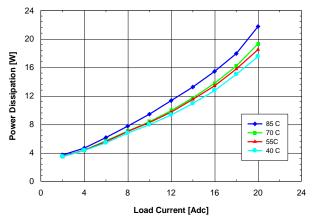


Figure 13: Power dissipation vs. load current and ambient temperature for converter w/o baseplate mounted vertically with Vin = 48 V and air flowing from pin 3 to pin 1 at a rate of 200 LFM (1.0 m/s).



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² Figures 3 & 4 <u>with</u> Baseplate, <u>Transverse</u> airflow, T_J ≤ 120 °C

³Figures 5 & 6 with Baseplate, Longitudinal airflow, T_J ≤ 120°C

⁴Figures 7 - 9 with baseplate, cold plate, heatsink combinations, $T_J \le 110 \, ^{\circ}\text{C}$

Figure 14: Turn-on transient at full rated load current (resistive) with Cout 10 μ F tantalum + 1 μ F ceramic at Vin = 48 V, triggered via ON/OFF pin. Top trace: ON/OFF signal (5 V/div.). Bottom trace: output voltage (5 V/div.). Time scale: 5 ms/div.

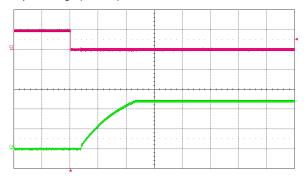


Figure 16: Output voltage response to load current step-change (10A – 15A – 10A) at Vin = 48V. Top trace: output voltage (100mV/div.). Bottom trace: load current (5A/div.). Current slew rate: 0.1A/μs. Co = 1μF ceramic + 10μF tantalum. Time scale: 200μs/div.

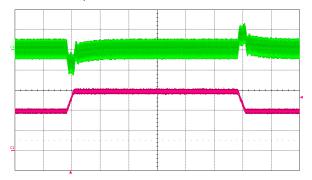


Figure 18: Output voltage ripple (20mV/div.) at full rated load current into a resistive load with Co = 10μF tantalum + 1μF ceramic and Vin = 48V. Time scale: 1μs/div.

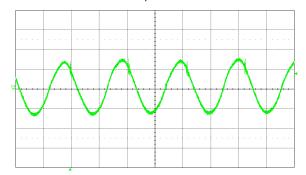


Figure 15: Turn-on transient at full rated load current (resistive) plus 10,000 µF at Vin = 48 V, triggered via ON/OFF pin. Top trace: ON/OFF signal (5 V/div.). Bottom trace: output voltage (5 V/div.). Time scale: 5 ms/div

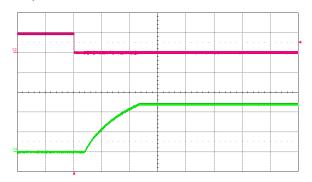


Figure 17: Output voltage response to load current step-change (10A – 15A – 10A) at Vin = 48V. Top trace: output voltage (200mV/div.). Bottom trace: load current (5A/div.). Current slew rate: 1A/μs. Co = 1μF ceramic + 100μF POS. Time scale: 200μs/div.

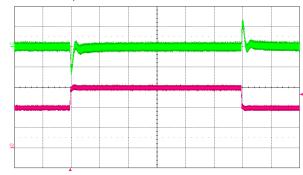


Figure 19: Test setup for measuring input reflected ripple currents, i_c and i_s .

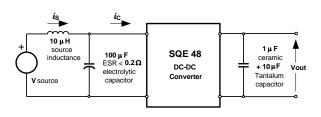


Figure 20: Input reflected ripple current, i_c (200mA/div.), measured at input terminals at full rated load current and Vin = 48V. Refer to Figure 32 for test setup. Time scale:1µs/div.

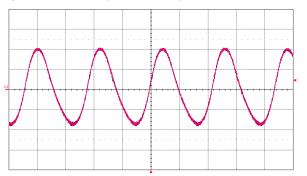


Figure 21: Input reflected ripple current, i_s (20 mA/div.), measured through 1 μ H at the source at full rated load current and Vin = 48V. Refer to Fig. 14 for test setup. Time scale: 2 μ s/div

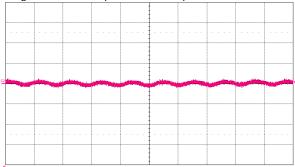


Figure 22: Load current (top trace, 20 A/div., 100 ms/div.) into a 10 m Ω short circuit during restart, at Vin = 48 V. Bottom trace (20 A/div., 1 ms/div.) is an expansion of the on-time portion of the top trace

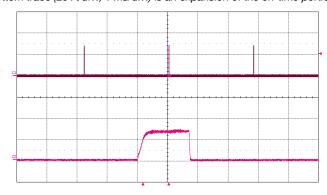
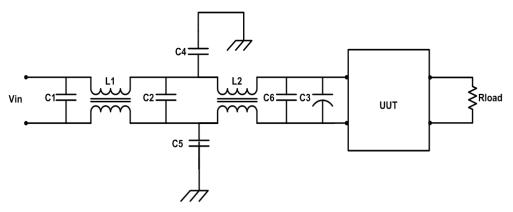


Figure 23: Typical input EMI filter circuit to attenuate conducted emissions



COMP. DES.	DESCRIPTION	
C1, C2, C6	(2EA, 6 capacitors) 1uF, 100V ceramic cap	
C3	33uF, 100V electrolytic cap	
L1, L2	0.59mH, Pulse P0353NL	
C4, C5	4,700pF, ceramic cap	

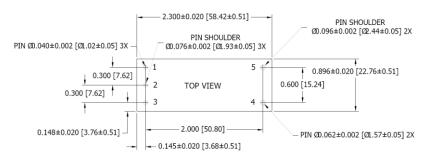


EMI Measurement EMI Meas 65 -Class B QP Class B AVG 60-55 -50 -45 -40 20-15 -10-150k 1M 10M 30M Hz

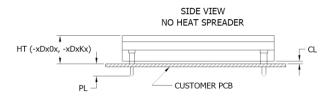
Figure 24: Input conducted emissions measurement (Typ.) of SQE48T20120. Conditions: V_{IN} =48VDC, I_{OUT} = 20AMPS

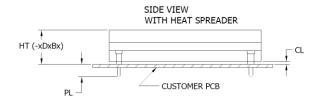
6 Physical Information

6.1 SQE48T PINOUT (THROUGH-HOLE)



PAD/PIN CONNECTIONS						
PAD/PIN #	FUNCTION					
1	V _{IN} (+)					
2	ON/OFF					
3	V _{IN} (-)					
4	V _{OUT} (-)					
5	V _{OUT} (+)					
5	V _{OUT} (+)					





PIN	PIN LENGTH [PL]
OPTION	±0.005" [±0.13]
Α	0.188" [4.78]
В	0.145" [3.68]

	HEIGHT [HT]	MIN CLEARAN CE [CL]	SPECIAL FEATURES
D	0.440" [11.18] Max	0.028" [0.71]	0
D	0.500" +/-0.020 [12.70 +/-0.51]	0.028" [0.71]	В

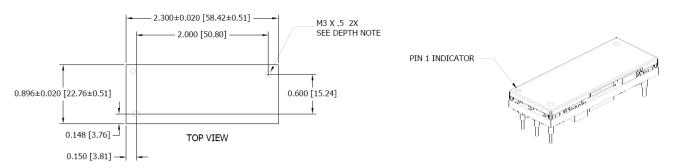


SQE48T Platform Notes

- All dimensions are in inches [mm]
- Pins 1-3 are Ø 0.040" [1.02] with Ø 0.076" [1.93] shoulder
- Pins 4 and 5 are Ø 0.062" [1.57] with are Ø 0.096" [2.44] shoulder
- Pin Material: Brass Alloy 360
- · Pin Finish: Tin over Nickel

6.2 Heat Spreader Interface Information

DEPTH NOTE: SCREW LENGTH MUST BE SELECTED TO LIMIT HEAT SPREADER PENETRATION TO 0.08 [2.0]



Note: Maximum allowable torque on heat spreader screw hole is 8kgF.cm

6.3 Converter Part Numbering / Odering Information

PRODUCT SERIES	INPUT VOLTAGE	MOUNTING SCHEME	RATED CURRENT	OUTPUT VOLTAGE	ON/OFF LOGIC	MAXIMUM HEIGHT [HT]	PIN LENGTH [PL]	SPECIAL FEATURES	RoHS
SQE	48	Т	20	120	- N	D	Α	В	G
One-Eighth Brick Format	36-75 V	T ⇒ Through- hole	20 ⇒ 20 ADC	120 ⇒ 12V	$\begin{array}{c} N \Rightarrow \\ Negative \\ P \Rightarrow \\ Positive \end{array}$	D ⇒ 0.440" for -xDx0x 0.520" for -xDxBx	Through hole A \Rightarrow 0.188" B \Rightarrow 0.145"	$0\Rightarrow Standard$ $B\Rightarrow$ Baseplate option	No Suffix ⇒ RoHS lead-solder- exemption compliant G ⇒ RoHS compliant for all six substances

The example above describes P/N SQE48T20120-NDABG: 36-75V input, through-hole, 20A@12V output, negative enable (ON/OFF logic), pin length of 0.188", maximum height of 0.52", 2250VDC isolation, no common mode capacitor, RoHS compliant for all 6 substances and integral heat spreader (Baseplate). Consult factory for availability of other options

For more information on these products consult: tech.support@psbel.com

NUCLEAR AND MEDICAL APPLICATIONS - Products are not designed or intended for use as critical components in life support systems, equipment used in hazardous environments, or nuclear control systems.

TECHNICAL REVISIONS - The appearance of products, including safety agency certifications pictured on labels, may change depending on the date manufactured. Specifications are subject to change without notice.

